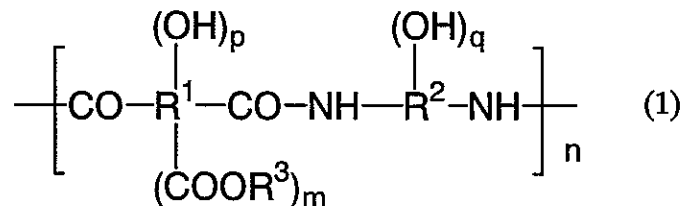


ABSTRACT OF THE DISCLOSURE

PHOTOSENSITIVE RESIN PRECURSOR COMPOSITION

The present invention relates to a positive photosensitive resin precursor composition which exhibits good storage stability after exposure.

A photosensitive resin precursor composition comprises (a) a polymer essentially composed of a structural unit expressed by formula (1); (b) at least two photo acid generators; and (c) a compound having an alkoxymethyl group:



wherein R^1 represents an organic group with a valence of 2 to 8, having at least two carbon atoms; R^2 represents an organic group with a valence of 2 to 6, having at least two carbon atoms; R^3 represents hydrogen or an organic group having a carbon number in the range of 1 to 20; n represents a number ranging from 10 to 100,000; m represents an integer in the range of 0 to 2; and p and q represent integers in the range of 0 to 4 and satisfy $p + q > 0$.